

Title (en)

Method for polishing a notch of a wafer

Title (de)

Verfahren zum Polieren der Einschnittteil einer Halbleiterscheibe

Title (fr)

Procédé de polissage pour l'encoche d'une plaquette semi-conductrice

Publication

**EP 1004400 A1 20000531 (EN)**

Application

**EP 99122257 A 19991108**

Priority

JP 33770098 A 19981127

Abstract (en)

A method for notch polishing by a notch-polishing unit (20) of an edge polisher is provided, in which evenness of polishing can be ensured by rotating a pad (32) for notch polishing in positive and reverse directions to polish a notch in a wafer (W). When the notch is polished by the pad (32) for notch polishing in the notch-polishing unit (20) formed of a sucking portion (30) for sucking a wafer (W) placed on the top surface thereof and the pad (32) for notch polishing rotatable by a driving source (33), the notch is evenly polished by rotating the pad (32) for notch polishing in positive and reverse directions. <IMAGE>

IPC 1-7

**B24B 9/06**

IPC 8 full level

**B24B 19/02** (2006.01); **B24B 9/00** (2006.01); **B24B 9/06** (2006.01)

CPC (source: EP KR)

**B24B 9/00** (2013.01 - KR); **B24B 9/065** (2013.01 - EP); **B24B 37/345** (2013.01 - EP)

Citation (search report)

- [Y] EP 0764976 A1 19970326 - SHINETSU HANDOTAI KK [JP]
- [Y] EP 0629470 A1 19941221 - SHINETSU HANDOTAI KK [JP], et al
- [A] DE 4325518 A1 19950202 - WACKER CHEMITRONIC [DE]
- [A] EP 0633097 A1 19950111 - SHINETSU HANDOTAI KK [JP], et al

Cited by

EP1291132A3; US7559825B2; DE102013204839A1; US9193026B2

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

**EP 1004400 A1 20000531**; JP 2000158315 A 20000613; KR 20000047734 A 20000725; TW 415880 B 20001221

DOCDB simple family (application)

**EP 99122257 A 19991108**; JP 33770098 A 19981127; KR 19990052942 A 19991126; TW 88119490 A 19991108